

Title (en)

Method for assembling micro injecting device and apparatus for the same

Title (de)

Verfahren zum Zusammenbau einer Mikrospritzvorrichtung und dazugehöriger Apparat

Title (fr)

Procédé d'assemblage d'un micro-dispositif d'injection et appareil pour sa mise en oeuvre

Publication

**EP 0999051 A2 20000510 (EN)**

Application

**EP 99308741 A 19991103**

Priority

RU 98119953 A 19981103

Abstract (en)

A method for assembling a micro-injecting device and an apparatus for assembling the device are disclosed. A heater chip wafer on which a plurality of heater chips are formed is fixed onto a vacuum bench, and a membrane manufactured independently of a jet chip is aligned to be separated by a predetermined space from the heater chip wafer, and the membrane is fixed on the heater chip wafer. This avoids the membrane being moved frequently in the process of aligning and assembling, thus obtaining in-advance prevention against damage to the membrane, and elimination of the necessity to align the membrane to each heater chip, thereby reducing significantly the time required for assembling. <IMAGE>

IPC 1-7

**B41J 2/14**

IPC 8 full level

**B41J 2/045** (2006.01); **B41J 2/04** (2006.01); **B41J 2/055** (2006.01); **B41J 2/14** (2006.01); **B41J 2/16** (2006.01)

CPC (source: EP KR)

**B41J 2/04** (2013.01 - KR); **B41J 2/14064** (2013.01 - EP); **B41J 2/1603** (2013.01 - EP); **B41J 2/1623** (2013.01 - EP); **B41J 2/1634** (2013.01 - EP); **B41J 2/1635** (2013.01 - EP)

Citation (applicant)

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Designated contracting state (EPC)

DE FR GB IT

DOCDB simple family (publication)

**EP 0999051 A2 20000510**; **EP 0999051 A3 20001108**; CN 1253038 A 20000517; JP 2000141668 A 20000523; JP 3045500 B2 20000529; KR 100288700 B1 20010416; KR 20000034823 A 20000626; RU 2144471 C1 20000120

DOCDB simple family (application)

**EP 99308741 A 19991103**; CN 99126093 A 19991103; JP 7733099 A 19990323; KR 19990007329 A 19990305; RU 98119953 A 19981103